Electronic Patent A	\pp	lication Fee	Transm	ittal			
Application Number:	10567733						
Filing Date:	10-Feb-2006						
Title of Invention:	Method for forming film, method for manufacturing semiconductor device, semiconductor device and substrate treatment system						
First Named Inventor/Applicant Name:	Kohei Kawamura						
Filer:	Marvin Jay Spivak/Yuriko Stankich						
Attorney Docket Number:	28	5995US26PCT					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing	Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 3 months with \$0 paid		1253	1	1110	1110		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
	Tot	1920		